Note from the Editor:

Welcome to the September 2016 e-newsletter of The Journal of Electronic Packaging (JEP). The newsletter, issued quarterly, will keep you abreast of the latest research developments in our field. Below you will find an opportunity to publish papers in JEP by March 2017, new review articles, ASE’s picks for industry readers, a link to the current issue, a special IMECE issue, information on how to publish IEEE conference papers in JEP, and JEP LinkedIn page. Thank you for taking the time to read this newsletter and please don’t hesitate to provide feedback by emailing me at my address below.

Sincerely,
YC Lee
Editor, Journal of Electronic Packaging
Leeyc@Colorado.edu

High quality papers to be reviewed and published in 2017!

There is room for high quality papers to be reviewed and published in March 2017 JEP issues. We have established a system that will make sure the initial review of every paper submitted to the journal will be completed in 8 weeks, and excellent papers can be published this year. You are welcome to submit your manuscript.

JEP Review Articles!

Four new review articles are published in the JEP and for a limited time these and other review articles are available for public access. The complete list of review articles is posted at http://electronicpackaging.org.


4. Measurement Techniques for Thermal Conductivity and Interfacial Thermal Conductance of Bulk and Thin Film Materials, Dongliang Zhao, Xin Qian, Xiaokun Gu, Saad Ayub Jajja, Ronggui Yang (University of Colorado); Dec. 2016

Click here to see the list of review articles published, to be published or to be submitted. Leaders in the field are invited to publish review articles on hot, emerging and fundamental topics. You are welcome to recommend topics and authors through our LinkedIn site.
ASE Picks- Selected Papers

The following are selected articles from recent issues of the Journal of Electronic Packaging which is of significant relevance to industry. The JEP Editorial Board extends its appreciation to Dr. Yi-Shao Lai of the ASE Group who selected these papers as a service to our readers. The ASE Group is the world’s largest provider of independent semiconductor manufacturing services in assembly and test.


Special Issue for ASME IMECE Papers

A Special issue of the Journal of Electronics Packaging will be published next June 2017, and will include outstanding invited IMECE papers of interest to the electronics and photonics packaging community. Papers will be nominated and invited by the Guest Editors Justin A. Weibel, and S. Ravi Annapragada who serve as Chairs of the track sponsored by the Electronic & Photonic Packaging Division (EPPD). Invited papers received prior to the submission deadline of December 16, 2016 will go through the Journal of Electronics Packaging (JEP) review process.

IEEE Conference Papers Submitted to JEP

You can you publish a high quality paper presented at an IEEE Conference in the ASME JEP. You have to make sure the scope of the paper is covered by JEP scope and the manuscript submitted has less than 75% of the contents of the
original IEEE conference paper. When the manuscript is approved for publication, you can get copyright permission at http://www.ieee.org/publications_standards/publications/rights/reqperm.html.

Current Issue

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Journal of Electronic Packaging (JEP) LinkedIn Page

Yes, 131 members have joined our LinkedIn page. We are developing a new companion web site to serve the JEP community. You will get to know the progress in real time. You are invited to join our JEP LinkedIn community (click on hyperlink) to join a network to serve electronic packaging researchers and engineers working in academic and industrial settings. This network is for editors, readers, authors, and reviewers to exchange information including calls for participation, new issues and free review articles.

About the Journal of Electronic Packaging

Editor, Y. C. Lee,
University of Colorado Boulder
JEP Home Page, Editorial Board.

The Journal of Electronic Packaging publishes papers that address 1) thermal management, applied mechanics and technologies for microsystems packaging; 2) critical issues in systems integration; 3) emerging packaging technologies and materials with micro/nano structures; and 4) general small scale systems. The journal is to serve researchers and engineers working in academic and industrial settings. Originality, scientific merit and high engineering relevance are the major criteria for the acceptance of a submitted paper. In addition, leaders in the field are invited to publish review articles on hot, emerging and fundamental topics. Send an email to leeyc@colorado.edu for any feedback or comments.